参考文献

TPLD1202 具有 I^{2}C/SPI 和 10 个 GPIO 的可编程逻辑器件

1 特性

- 工作特性
  - 工作温度范围：-40°C 至 125°C
  - 宽电源电压范围：1.71V 至 5.5V
- 可配置的宏单元
  - 2 位、3 位和 4 位查询表
  - 具有和不具有复位/置位选项的 D 型触发器或锁存器
  - 8 位移位寄存器
  - 16 位图形发生器
  - 计数器和延迟发生器
  - PWM 发生器
  - 可编程抗尖峰脉冲滤波器或边沿检测器
  - 多通道采样模拟比较器
  - 电压基准和模拟温度传感器
  - 振荡器
- 灵活的数字 I/O 功能
  - 所有数字信号均可连接任意 GPIO
  - 数字输入模式：带和不带施密特触发器的数字输入，低电压数字输入
  - 数字输出模式：推挽、开漏 NMOS、三态
- 开发工具
  - InterConnect Studio
  - TPLD1202 评估模块
  - TPLD 编程板

2 应用

- 工厂自动化与控制
- 通信设备
- 零售自动化和支付
- 测试与测量
- 专业音频、视频和标牌
- 个人电子产品

3 说明

TPLD1202 是 TI 可编程逻辑器件 (TPLD) 系列器件中的一款，具有多用途可编程逻辑 IC，支持组合逻辑、顺序逻辑和模拟块。TPLD 提供了一个完全集成的低功耗解决方案来实现常见的系统功能，例如时序延迟、电压监控器、系统复位、电源序列发生器、I/O 扩展器等。此器件具有可配置的 I/O 结构，扩展了混合信号环境中的兼容性，减少了所需的分立式元件的数量。

系统设计人员可以通过 InterConnect Studio 创建电路并配置宏蜂窝、I/O 引脚和互连，方法是临时模拟非易失性存储器或对一次性可编程 (OTP) 进行永久编程。TPLD1202 由硬件和软件生态系统提供支持，配备应用手册、参考设计和设计示例。如需了解详情和访问设计工具，请访问 ti.com。

器件信息

器件型号	封装[1]	本体尺寸（标称值）
TPLD1202	DYY（SOT-23-THN，14）	2.00mm x 4.20mm
	RWB（X2QFN，12）	1.60mm x 1.60mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

English Data Sheet: SCPS300

内容

4 器件和文档支持

4.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击*通知*进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

4.2 支持资源

TI E2E™ 中文支持论坛是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的使用条款。

4.3 商标

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

4.4 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

4.5 术语表

TI 术语表	本术语表列出并解释了术语、首字母缩略词和定义。

5 修订历史记录

注：以前版本的页码可能与当前版本的页码不同

日期	修订版本	注释
2024 年 9 月	*	预告信息发布

6 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件可用的最新数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。有关此数据表的浏览器版本，请查阅左侧的导航栏。

6.1 封装选项附录

封装信息

可订购器件	状态 (1)	封装类型	封装图	引脚	包装数量	环保计划 (2)	铅/焊球镀层(4)	MSL 峰值温度(3)	工作温度 (°C)	器件标识(5) (6)
PTPLD1202RWBR	预发布	X2QFN	RWB	12	3000	RoHS 和绿色环保	NIPDAU	Level-1-260C-UNLIM	-40 至 125	P2
PTPLD1202DYYR	预发布	SOT-23-THN	DYY	14	3000	RoHS 和绿色环保	SN	Level-1-260C-UNLIM	-40 至 125	P1202

(1) 销售状态值定义如下：
正在供货：建议用于新设计的产品器件。
限期购买：TI 已宣布器件即将停产，但仍在购买期限内。
NRND：不推荐用于新设计。为支持现有客户，器件仍在生产，但 TI 不建议在新设计中使用此器件。
PRE_PROD：器件未发布，尚未量产，未向大众市场供货，也未在网络上供应，未提供样片。
预发布：器件已发布，但未量产。可能提供样片，也可能无法提供样片。
已停产：TI 已停止生产该器件。

(2) 环保计划 - 规划的环保分级包括：无铅 (RoHS)，无铅（RoHS 豁免）或绿色环保（RoHS，无锑/溴）- 如需了解最新供货信息及更多产品内容详情，请访问 http://www.ti.com/productcontent。
待定：无铅/绿色环保转换计划尚未确定。
无铅 (RoHS)：TI 所说的“无铅”或“无 Pb”是指半导体产品符合针对所有 6 种物质的现行 RoHS 要求，包括要求铅的重量不超过同质材料总重量的 0.1%。因在设计时就考虑到了高温焊接要求，因此 TI 的无铅产品适用于指定的无铅作业。
无铅（RoHS 豁免）：该元件在以下两种情况下可享受 RoHS 豁免：1) 芯片和封装之间使用铅基倒装芯片焊接凸点；2) 芯片和引线框之间使用铅基芯片粘合剂。否则，元件将根据上述规定视为无铅（符合 RoHS）。
绿色环保（RoHS，无锑/溴）：TI 将“绿色环保”定义为无铅（符合 RoHS 标准）、无溴 (Br) 和无锑 (Sb) 基阻燃剂（Br 或 Sb 在同质材料中的质量不超过总质量的 0.1%）

(3) MSL，峰值温度-- 湿敏等级额定值（符合 JEDEC 工业标准分级）和峰值焊接温度。

(4) 铅/焊球镀层 - 可订购器件可能有多种镀层材料选项。各镀层选项用垂直线隔开。如果铅/焊球镀层值超出最大列宽，则会折为两行。

(5) 器件上可能还有与标识、批次跟踪代码或环境分级相关的标记

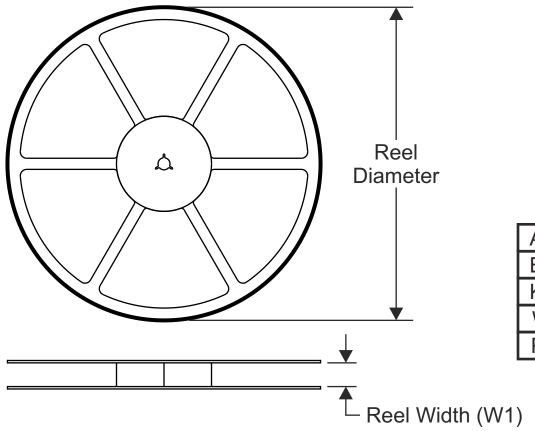
(6) 如有多个器件标识，将用括号括起来。不过，器件上仅显示括号中以“~”隔开的其中一个器件标识。如果某一行缩进，说明该行续接上一行，这两行合在一起表示该器件的完整器件标识。

重要信息和免责声明：本页面上提供的信息代表 TI 在提供该信息之日的认知和观点。TI 的认知和观点基于第三方提供的信息，TI 不对此类信息的正确性做任何声明或保证。TI 正在致力于更好地整合第三方信息。TI 已经并将继续采取合理的措施来提供有代表性且准确的信息，但是可能尚未对引入的原料和化学制品进行破坏性测试或化学分析。TI 和 TI 供应商认为某些信息属于专有信息，因此可能不会公布其 CAS 编号及其他受限制的信息。

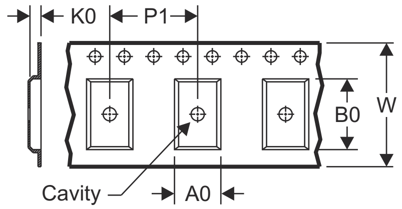
在任何情况下，TI 因此类信息产生的责任决不超过 TI 每年向客户销售的本文档所述 TI 器件的总购买价。

6.2 卷带包装信息

REEL DIMENSIONS

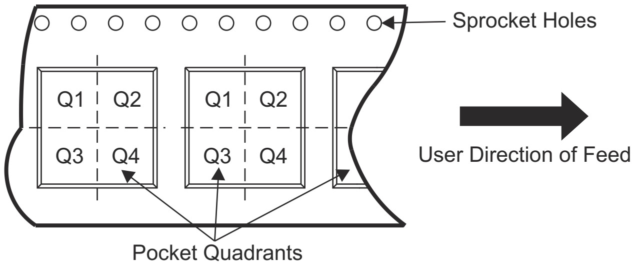


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

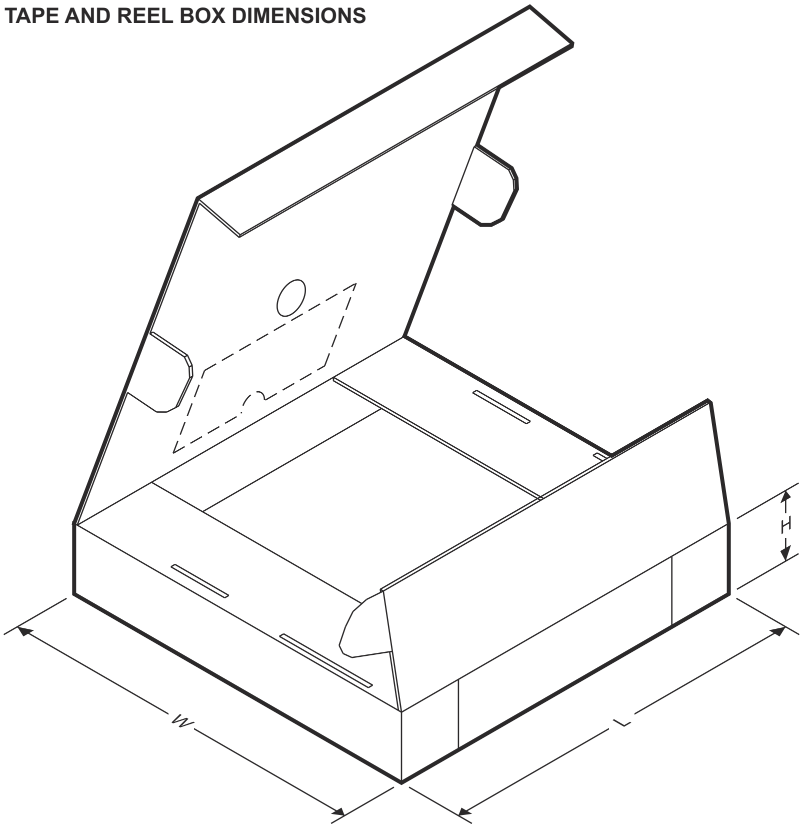
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



器件	封装类型	封装图	引脚	SPQ	卷带直径 (mm)	卷带宽度 W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 象限
PTPLD1202RWBR	X2QFN	RWB	12	3000	180	8.4	1.8	1.8	0.48	4	8	2
PTPLD1202DYYR	SOT-23-THN	DYY	12	3000	180	8.4	4.5	3.56	1.35	8	12	3

ADVANCE INFORMATION

TAPE AND REEL BOX DIMENSIONS



器件	封装类型	封装图	引脚	SPQ	长度 (mm)	宽度 (mm)	高度 (mm)
PTPLD1202RWBR	X2QFN	RWB	12	3000	210	185	35
PTPLD1202DYYR	SOT-23-THN	DYY	12	3000	210	185	35

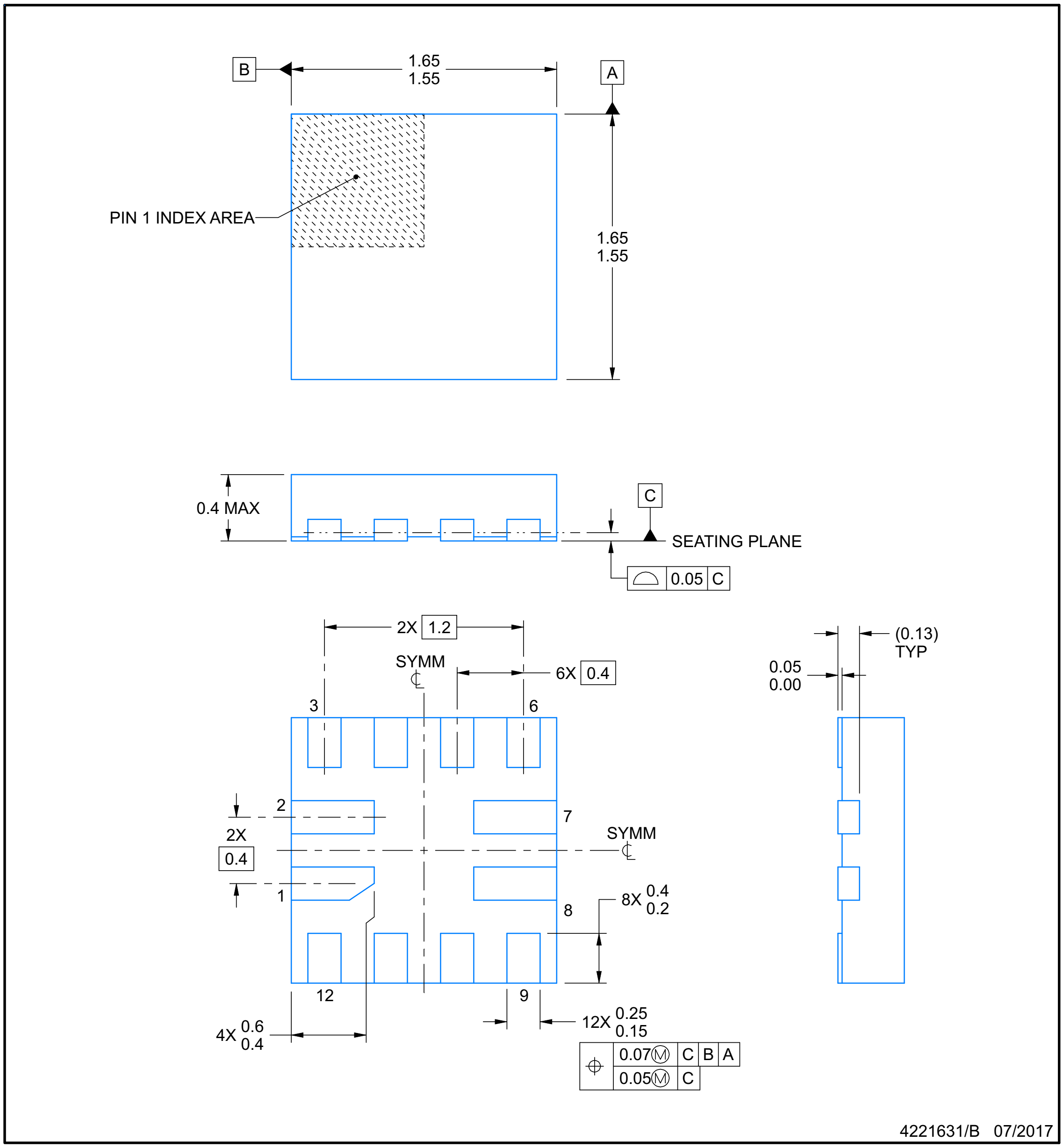
6.3 机械数据

PACKAGE OUTLINE

RWB0012A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

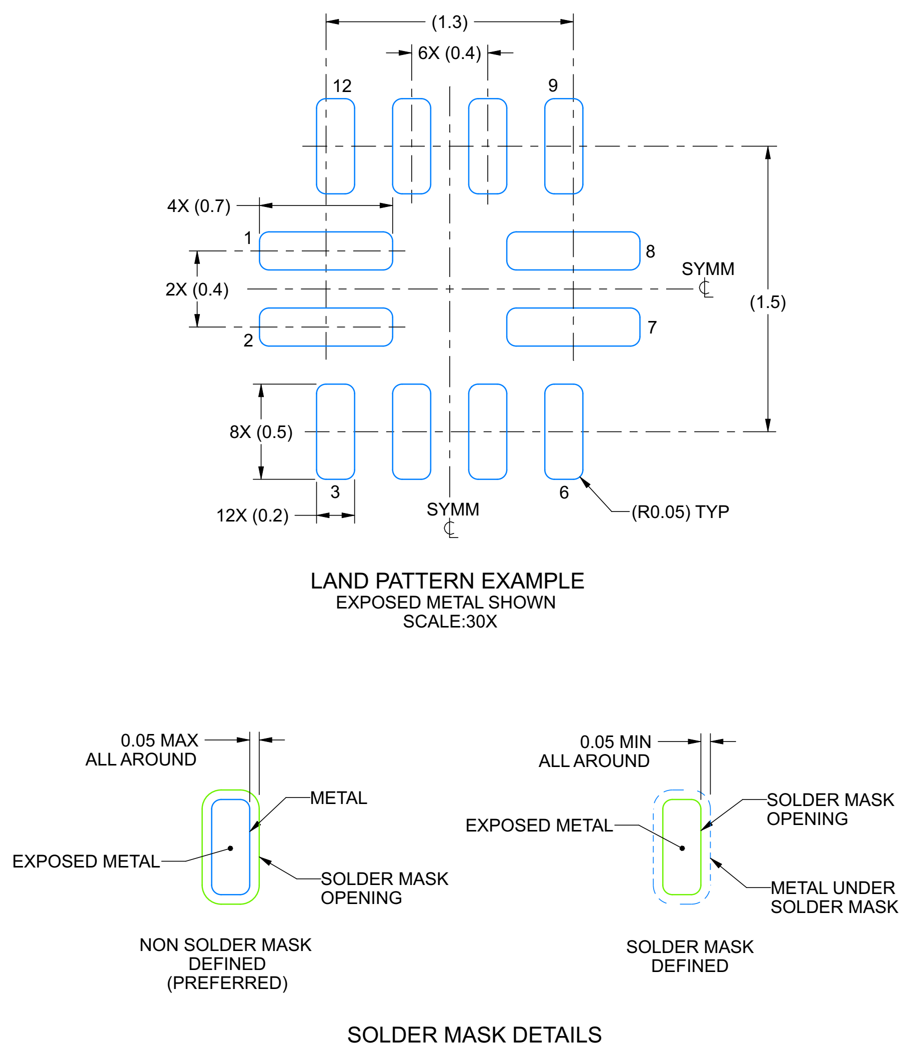
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

RWB0012A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:30X

NON SOLDER MASK
DEFINED
(PREFERRED)

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4221631/B 07/2017

NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

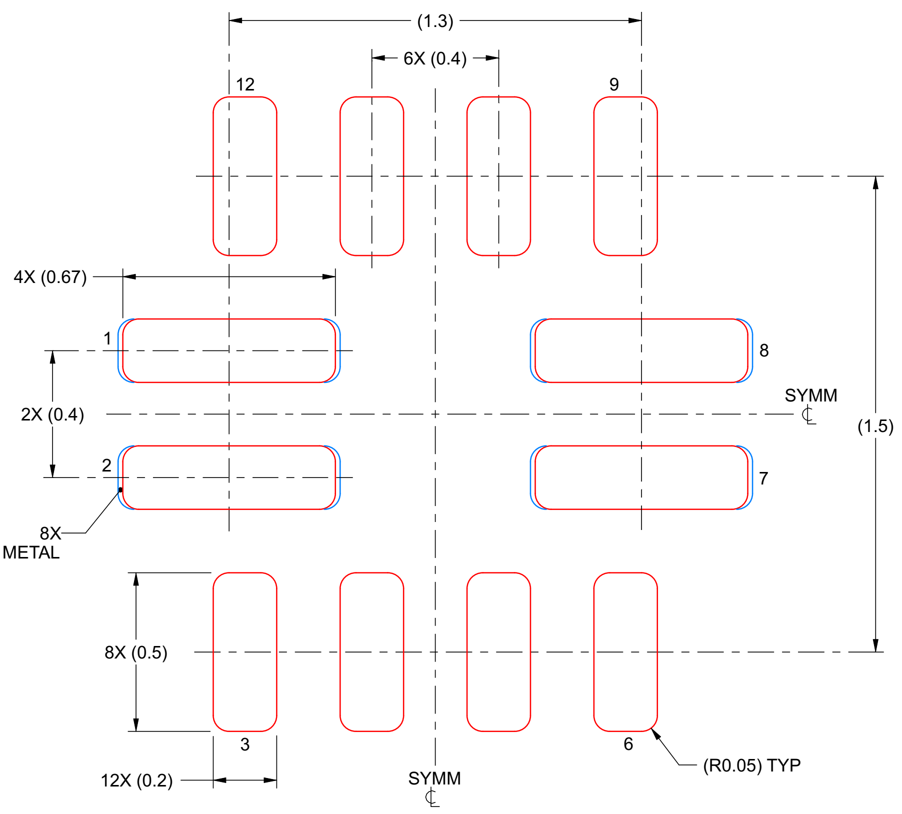
www.ti.com

EXAMPLE STENCIL DESIGN

RWB0012A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

PADS 1,2,7 & 8
96% PRINTED SOLDER COVERAGE BY AREA
SCALE:50X

4221631/B 07/2017

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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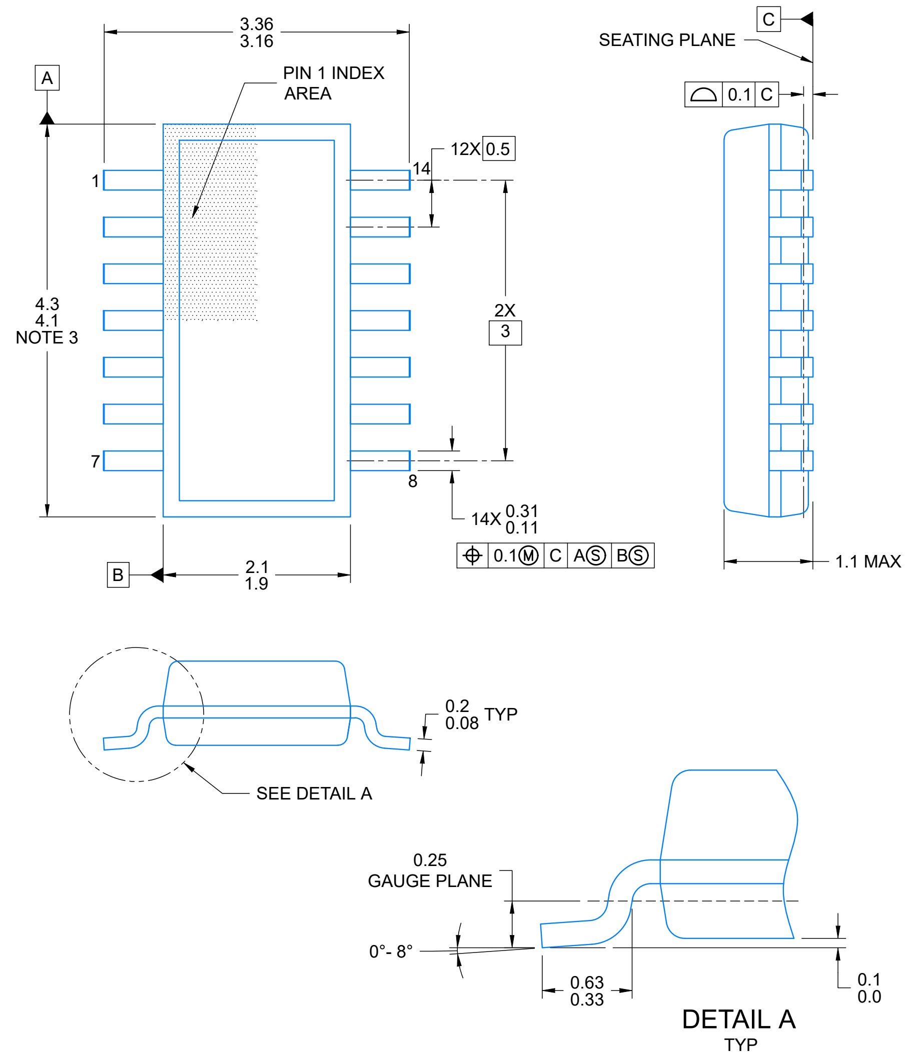
ADVANCE INFORMATION

PACKAGE OUTLINE

DYY0014A

SOT-23-THIN - 1.1 mm max height

PLASTIC SMALL OUTLINE



4224643/B 07/2021

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
5. Reference JEDEC Registration MO-345, Variation AB

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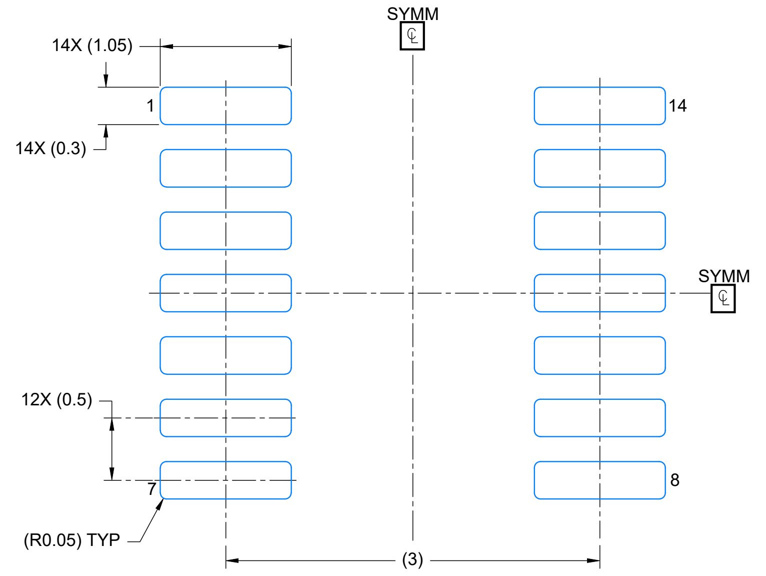
ADVANCE INFORMATION

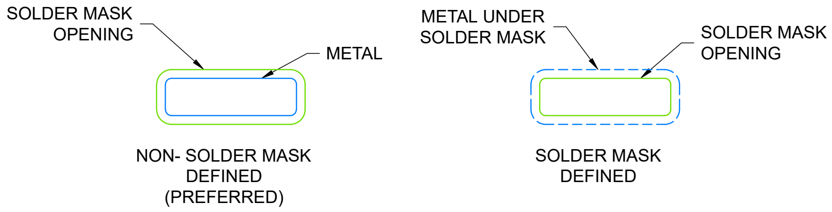
EXAMPLE BOARD LAYOUT

DYY0014A **SOT-23-THIN - 1.1 mm max height**

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



SOLDER MASK DETAILS

4224643/B 07/2021

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

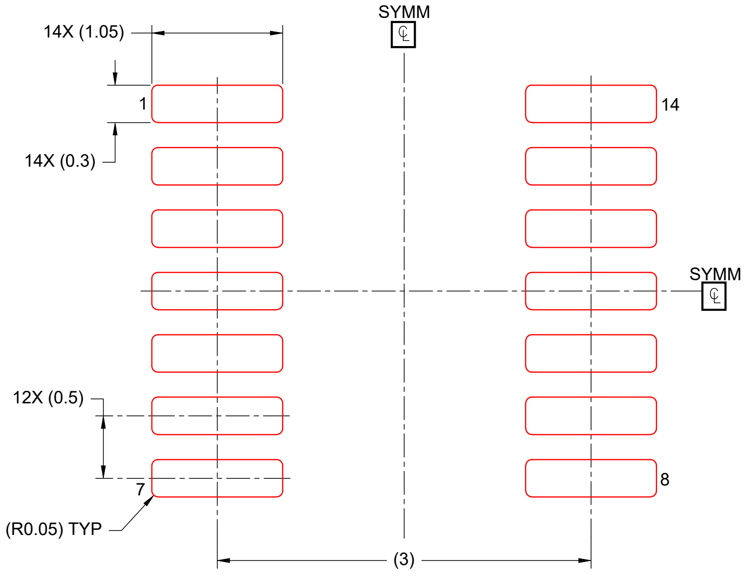
TEXAS INSTRUMENTS
www.ti.com

ADVANCE INFORMATION

EXAMPLE STENCIL DESIGN

DYY0014A **SOT-23-THIN - 1.1 mm max height**

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 20X

4224643/B 07/2021

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

TEXAS INSTRUMENTS
www.ti.com

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
PTPLD1202DYYR	Active	Preproduction	SOT-23-THIN (DYY) | 14	3000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
PTPLD1202DYYR.A	Active	Preproduction	SOT-23-THIN (DYY) | 14	3000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
PTPLD1202RWBR	Active	Preproduction	X2QFN (RWB) | 12	3000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
PTPLD1202RWBR.A	Active	Preproduction	X2QFN (RWB) | 12	3000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	
PTPLD1202RWSR	Active	Preproduction	X2QFN (RWS) | 12	3000 | LARGE T&R	-	Call TI	Call TI	-40 to 125	

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TPLD1202 :

- Automotive : TPLD1202-Q1

NOTE: Qualified Version Definitions:

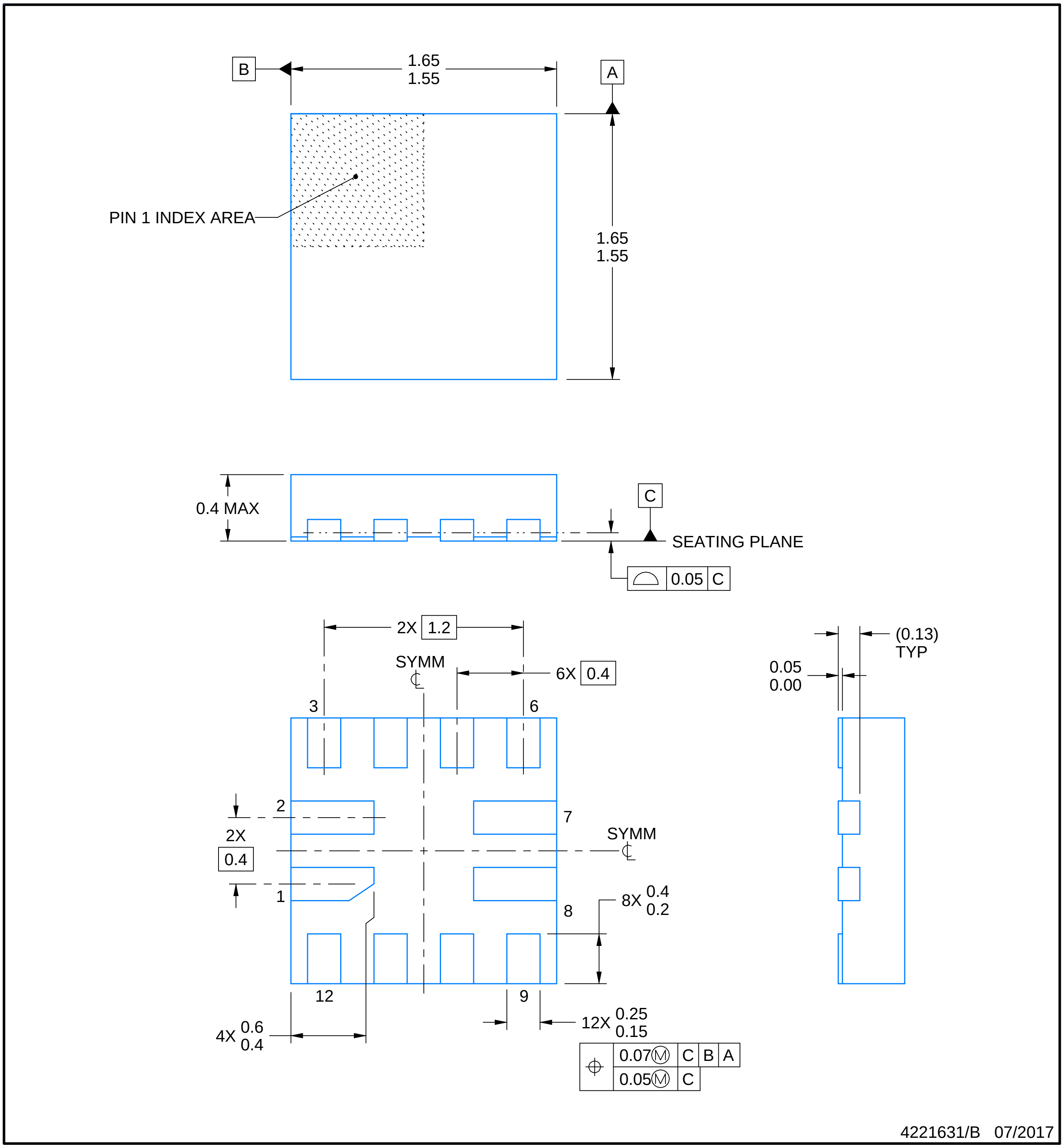
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE OUTLINE

RWB0012A

X2QFN - 0.4 mm max height

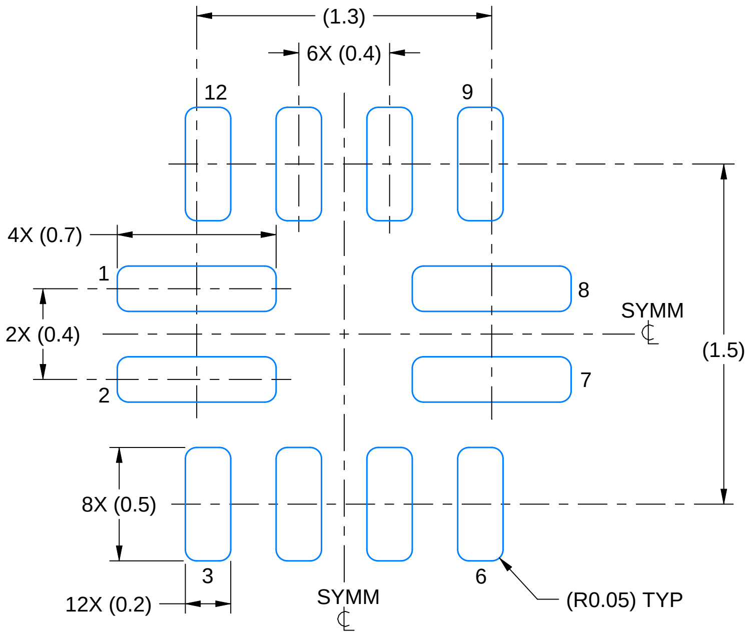
PLASTIC QUAD FLATPACK - NO LEAD



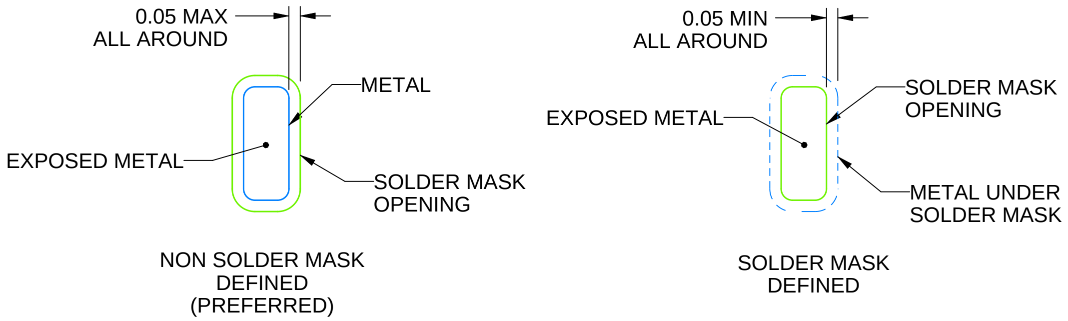
4221631/B 07/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:30X

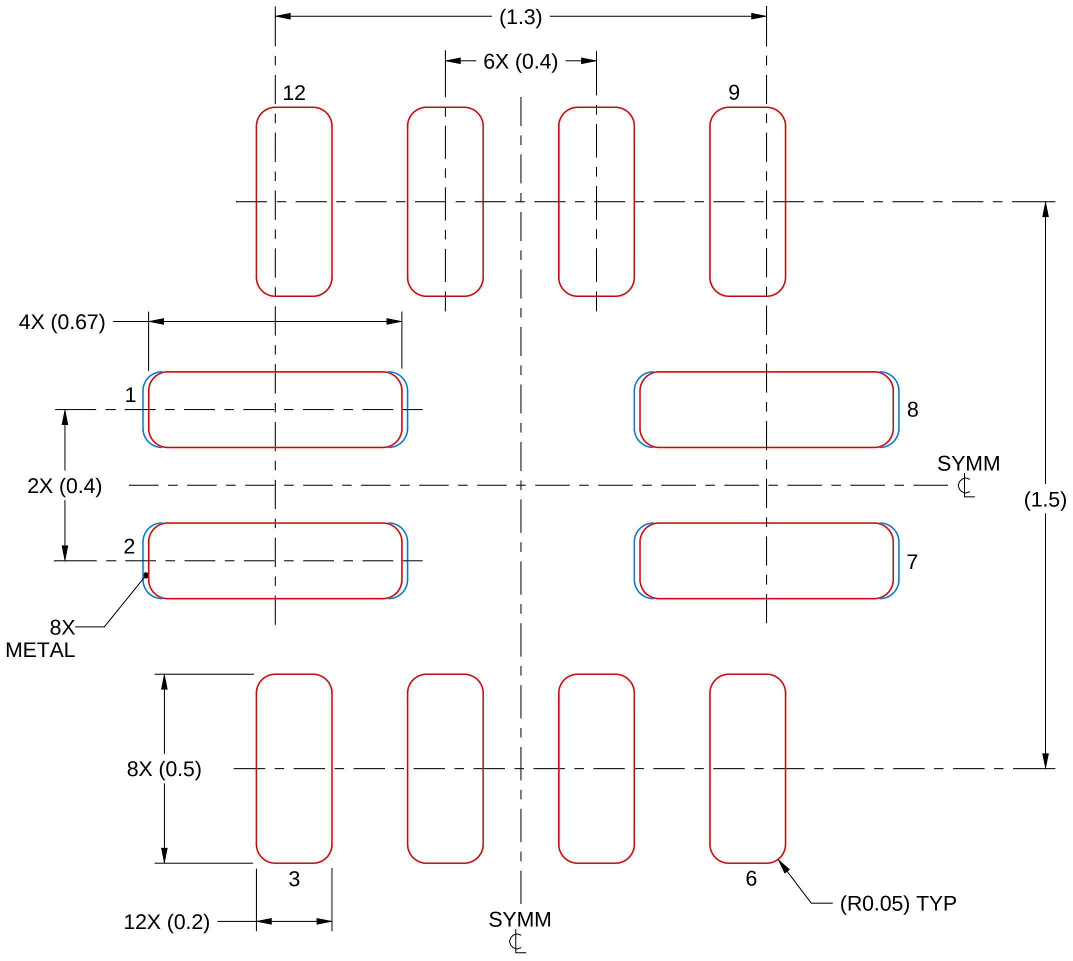


SOLDER MASK DETAILS

4221631/B 07/2017

NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

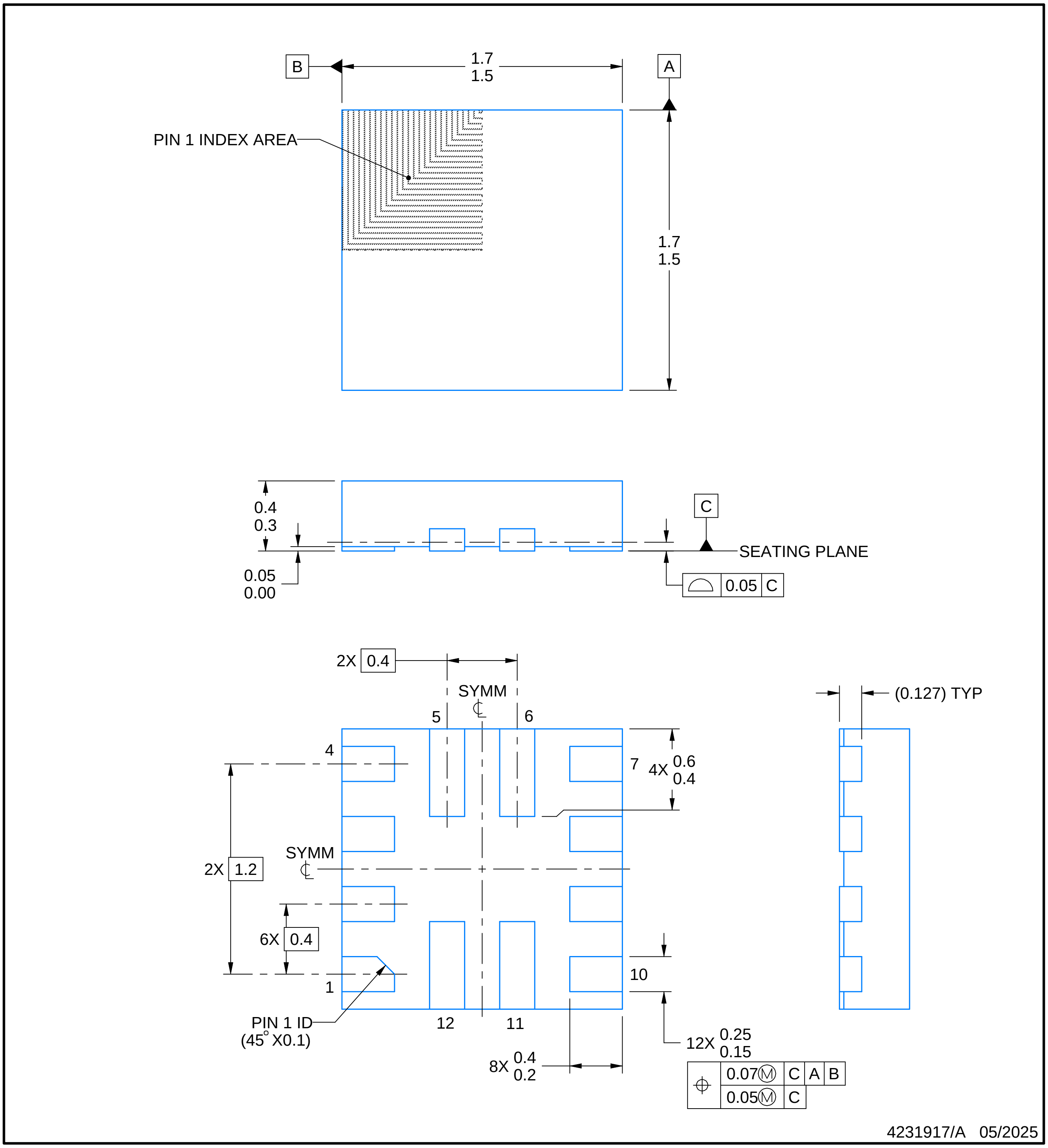


SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

PADS 1,2,7 & 8
96% PRINTED SOLDER COVERAGE BY AREA
SCALE:50X

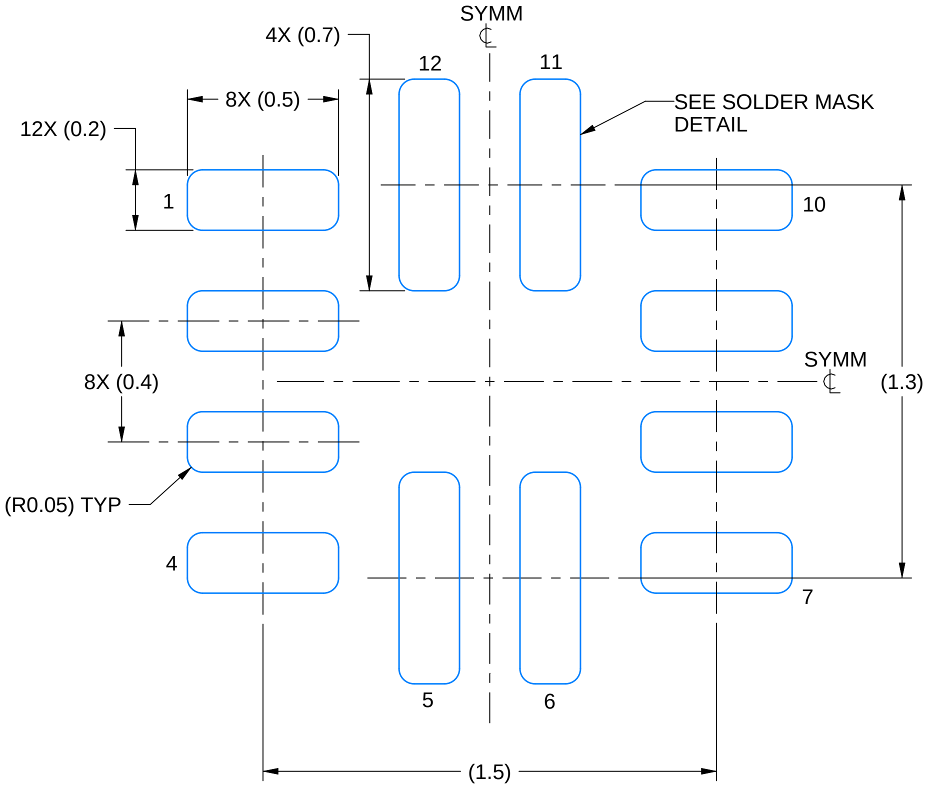
NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

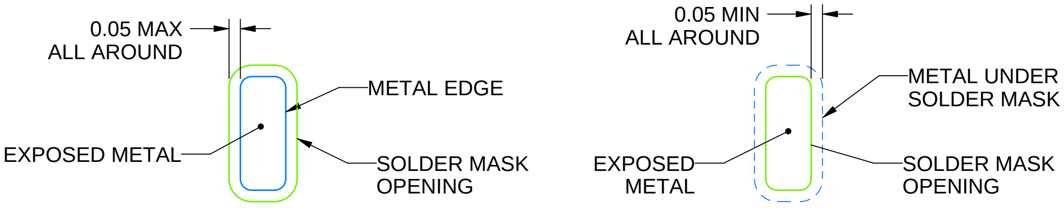


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 40X



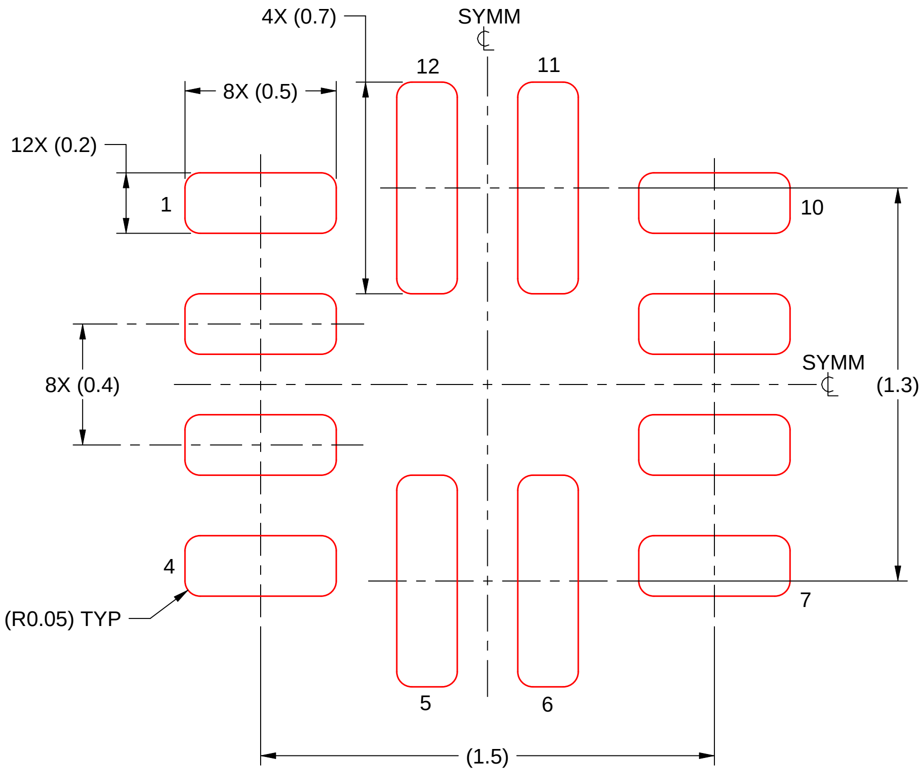
NON SOLDER MASK
DEFINED
(PREFERRED)

SOLDER MASK DEFINED

SOLDER MASK DETAILS

NOTES: (continued)

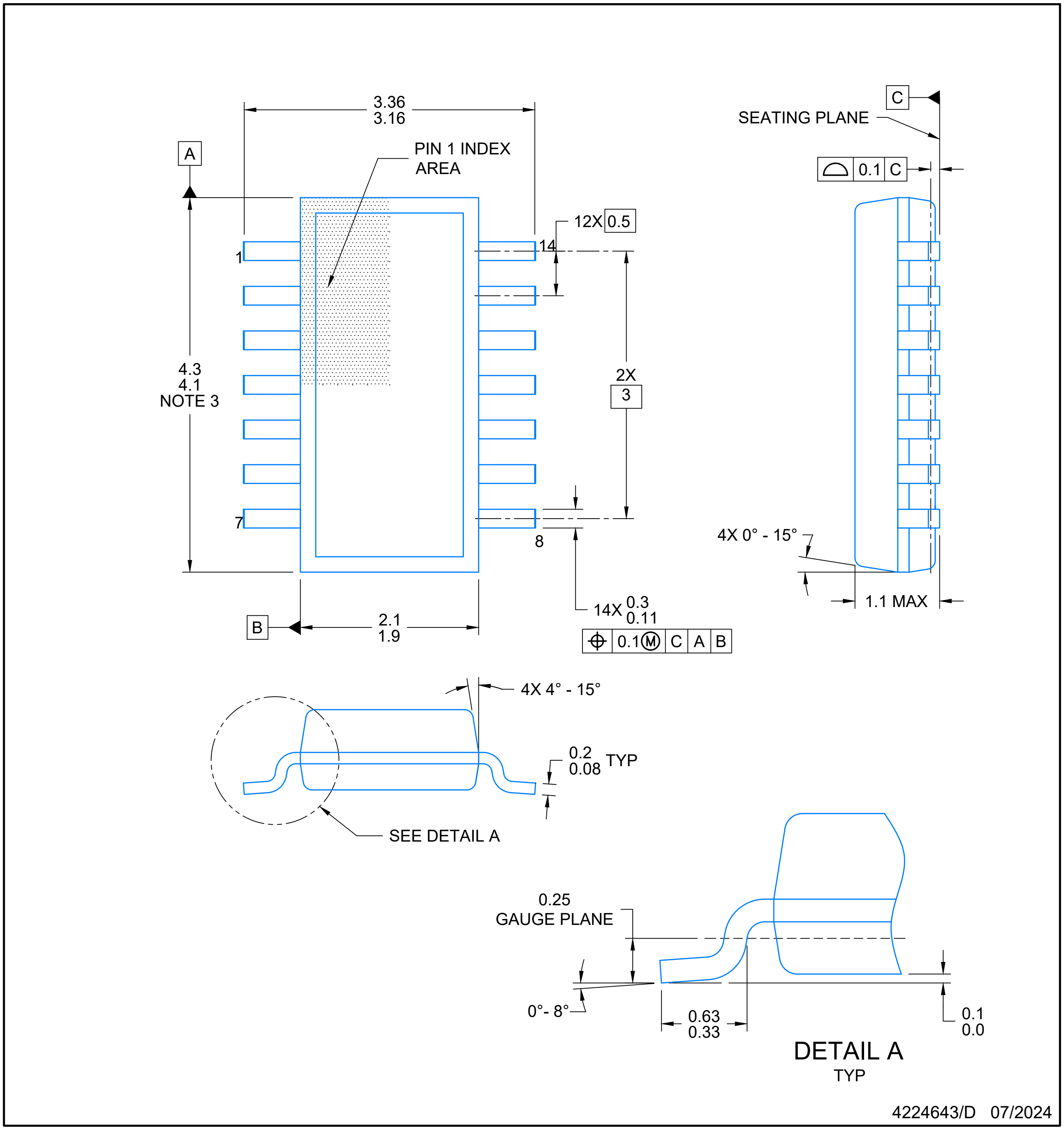
3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



SOLDER PASTE EXAMPLE
BASED ON 0.1 MM THICK STENCIL
SCALE: 40X

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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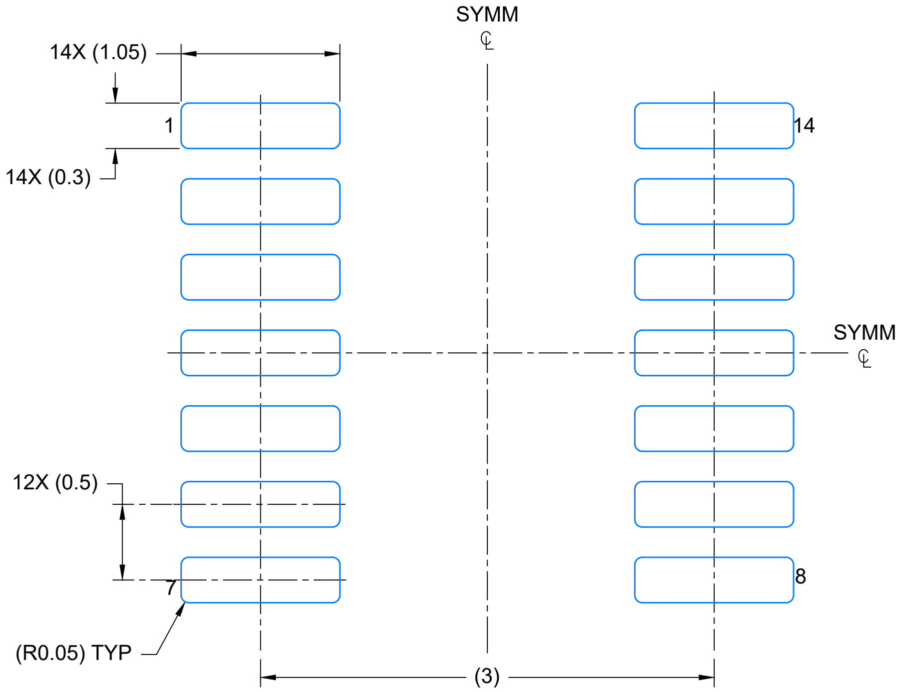
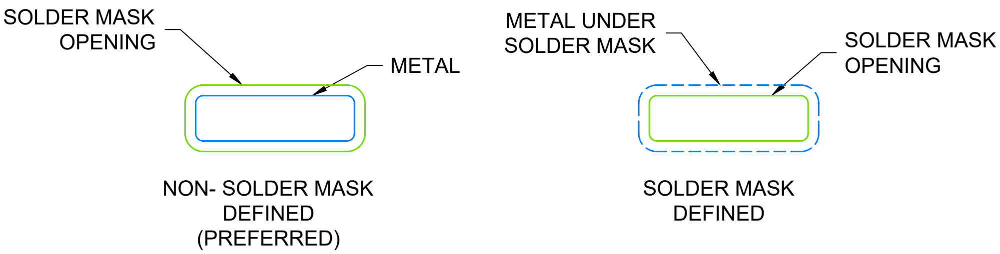
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
5. Reference JEDEC Registration MO-345, Variation AB



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



SOLDER MASK DETAILS

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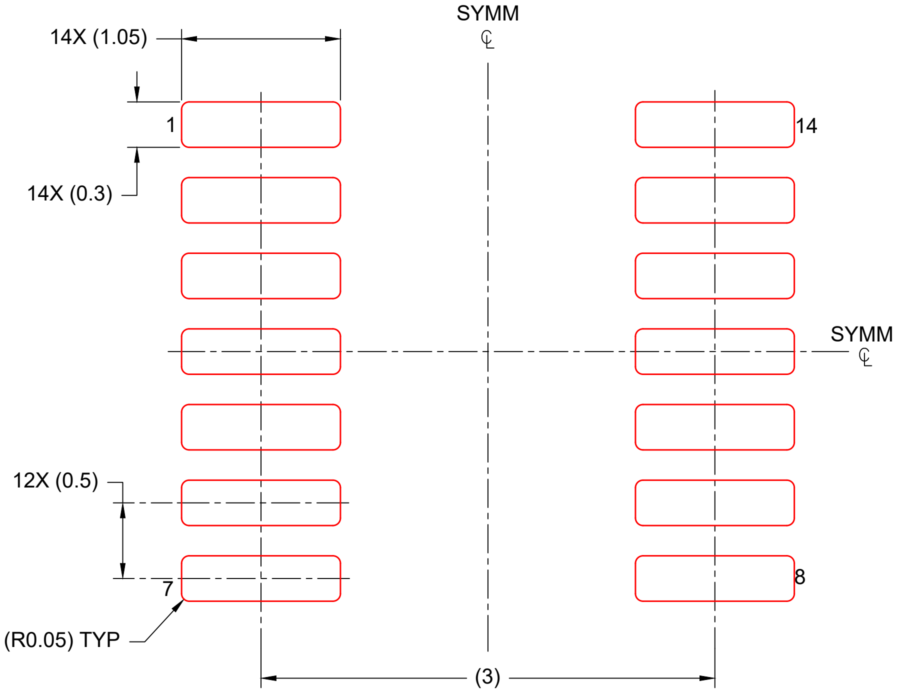
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 20X

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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最后更新日期：2025 年 10 月